

**PrimePACK™3+ B-series module with TRENCHSTOP™ IGBT7 and emitter controlled 7 diode and NTC / pre-applied thermal interface material**

**Features**

- Electrical features
  - $V_{CES} = 1200\text{ V}$
  - $I_{C\text{nom}} = 2400\text{ A} / I_{CRM} = 4800\text{ A}$
  - High current density
  - Low inductive design
  - Low  $V_{CE,\text{sat}}$
  - $T_{vj,\text{op}} = 150^\circ\text{C}$
  - Overload operation up to  $175^\circ\text{C}$
  - TRENCHSTOP™ IGBT7
- Mechanical features
  - High creepage and clearance distances
  - High power density
  - Package with CTI > 400
  - Pre-applied thermal interface material



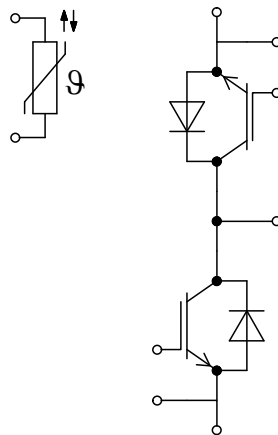
**Potential applications**

- Three-level applications
- Solar applications
- Energy storage systems

**Product validation**

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

**Description**



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## 1 Package

**Table 1** Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	$V_{ISOL}$	RMS, $f = 50$ Hz	4.0	kV
Material of module baseplate			Cu	
Creepage distance	$d_{Creep}$	terminal to heatsink	36.0	mm
Creepage distance	$d_{Creep}$	terminal to terminal	28.0	mm
Clearance	$d_{Clear}$	terminal to heatsink	21.0	mm
Clearance	$d_{Clear}$	terminal to terminal	19.0	mm
Comparative tracking index	$CTI$		>400	

**Table 2** Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Stray inductance module	$L_{SCE}$			5		nH
Module lead resistance, terminals - chip	$R_{AA'+CC'}$	$T_H=25^\circ\text{C}$ , per switch		0.045		m $\Omega$
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	$T_H=25^\circ\text{C}$ , per switch		0.045		m $\Omega$
Storage temperature	$T_{stg}$		-40		150	$^\circ\text{C}$
Maximum baseplate operation temperature	$T_{BPmax}$				150	$^\circ\text{C}$
Mounting torque for module mounting	$M$	- Mounting according to valid application note	M5, Screw	3	6	Nm
Terminal connection torque	$M$	- Mounting according to valid application note	M4, Screw	1.8	2.1	Nm
			M8, Screw	8	10	
Weight	$G$			1400		g

## 2 IGBT, 3-Level

**Table 3** Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Collector-emitter voltage	$V_{CES}$	$T_{vj} = 25^\circ\text{C}$	1200	V
Implemented collector current	$I_{CN}$		2400	A
Continuous DC collector current	$I_{CDC}$	$T_{vj\ max} = 150^\circ\text{C}$ $T_H = 30^\circ\text{C}$	2400	A

(table continues...)

**Table 3 (continued) Maximum rated values**

Parameter	Symbol	Note or test condition	Values	Unit
Repetitive peak collector current	$I_{CRM}$	$t_p$ limited by $T_{vj\ op}$	4800	A
Gate-emitter peak voltage	$V_{GES}$		±20	V

**Table 4 Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter saturation voltage	$V_{CE\ sat}$	$I_C = 2400\ A, V_{GE} = 15\ V$	$T_{vj} = 25\ ^\circ C$	1.27	1.79	V
			$T_{vj} = 125\ ^\circ C$	1.37	1.82	
			$T_{vj} = 150\ ^\circ C$	1.40	1.84	
Gate threshold voltage	$V_{GEth}$	$I_C = 48\ mA, V_{CE} = V_{GE}, T_{vj} = 25\ ^\circ C$	5.15	5.80	6.45	V
Gate charge	$Q_G$	$V_{GE} = \pm 15\ V, V_{CE} = 600\ V$		38.1		μC
Internal gate resistor	$R_{Gint}$	$T_{vj} = 25\ ^\circ C$		0.23		Ω
Input capacitance	$C_{ies}$	$f = 100\ kHz, T_{vj} = 25\ ^\circ C, V_{CE} = 25\ V, V_{GE} = 0\ V$		325		nF
Reverse transfer capacitance	$C_{res}$	$f = 100\ kHz, T_{vj} = 25\ ^\circ C, V_{CE} = 25\ V, V_{GE} = 0\ V$		1.92		nF
Collector-emitter cut-off current	$I_{CES}$	$V_{CE} = 1200\ V, V_{GE} = 0\ V$			5	mA
Gate-emitter leakage current	$I_{GES}$	$V_{CE} = 0\ V, V_{GE} = 20\ V, T_{vj} = 25\ ^\circ C$			400	nA
Turn-on delay time (inductive load)	$t_{don}$	$I_C = 2400\ A, V_{CE} = 600\ V, V_{GE} = \pm 15\ V, R_{Gon} = 0.4\ \Omega$	$T_{vj} = 25\ ^\circ C$	0.645		μs
			$T_{vj} = 125\ ^\circ C$	0.785		
			$T_{vj} = 150\ ^\circ C$	0.820		
Rise time (inductive load)	$t_r$	$I_C = 2400\ A, V_{CE} = 600\ V, V_{GE} = \pm 15\ V, R_{Gon} = 0.4\ \Omega$	$T_{vj} = 25\ ^\circ C$	0.185		μs
			$T_{vj} = 125\ ^\circ C$	0.210		
			$T_{vj} = 150\ ^\circ C$	0.215		
Turn-off delay time (inductive load)	$t_{doff}$	$I_C = 2400\ A, V_{CE} = 600\ V, V_{GE} = \pm 15\ V, R_{Goff} = 3.3\ \Omega$	$T_{vj} = 25\ ^\circ C$	2.800		μs
			$T_{vj} = 125\ ^\circ C$	2.900		
			$T_{vj} = 150\ ^\circ C$	3.000		
Fall time (inductive load)	$t_f$	$I_C = 2400\ A, V_{CE} = 600\ V, V_{GE} = \pm 15\ V, R_{Goff} = 3.3\ \Omega$	$T_{vj} = 25\ ^\circ C$	0.205		μs
			$T_{vj} = 125\ ^\circ C$	0.245		
			$T_{vj} = 150\ ^\circ C$	0.275		
Turn-on energy loss per pulse	$E_{on}$	$I_C = 2400\ A, V_{CE} = 600\ V, L_\sigma = 50\ nH, V_{GE} = \pm 15\ V, R_{Gon} = 0.4\ \Omega, di/dt = 9000\ A/\mu s (T_{vj} = 150\ ^\circ C)$	$T_{vj} = 25\ ^\circ C$	110		mJ
			$T_{vj} = 125\ ^\circ C$	205		
			$T_{vj} = 150\ ^\circ C$	240		

(table continues...)

**Table 4 (continued) Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Turn-off energy loss per pulse	$E_{off}$	$I_C = 2400\text{ A}$ , $V_{CE} = 600\text{ V}$ , $L_\sigma = 50\text{ nH}$ , $V_{GE} = \pm 15\text{ V}$ , $R_{Goff} = 3.3\ \Omega$ , $dv/dt = 1030\text{ V}/\mu\text{s}$ ( $T_{vj} = 150\text{ }^\circ\text{C}$ )	$T_{vj} = 25\text{ }^\circ\text{C}$		715	mJ
			$T_{vj} = 125\text{ }^\circ\text{C}$		845	
			$T_{vj} = 150\text{ }^\circ\text{C}$		890	
Thermal resistance, junction to heat sink	$R_{thJH}$	per IGBT, Valid with IFX pre-applied Thermal Interface Material			27.6	K/kW
Temperature under switching conditions	$T_{vj\ op}$		-40		150	$^\circ\text{C}$

Note:  $R_{thJH}$  max. value is valid for  $T_C = 110\text{ }^\circ\text{C}$ .

### 3 Diode, 3-Level

**Table 5 Maximum rated values**

Parameter	Symbol	Note or test condition	Values	Unit
Repetitive peak reverse voltage	$V_{RRM}$	$T_{vj} = 25\text{ }^\circ\text{C}$	1200	V
Continuous DC forward current	$I_F$		2400	A
Repetitive peak forward current	$I_{FRM}$	$t_p = 1\text{ ms}$	4800	A

**Table 6 Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Forward voltage	$V_F$	$I_F = 2400\text{ A}$ , $V_{GE} = 0\text{ V}$	$T_{vj} = 25\text{ }^\circ\text{C}$		1.70	2.03	V
			$T_{vj} = 125\text{ }^\circ\text{C}$		1.65	1.96	
			$T_{vj} = 150\text{ }^\circ\text{C}$		1.60	1.94	
Peak reverse recovery current	$I_{RM}$	$I_F = 2400\text{ A}$ , $V_R = 600\text{ V}$ , $V_{GE} = -15\text{ V}$ , $-di_F/dt = 6850\text{ A}/\mu\text{s}$ ( $T_{vj} = 150\text{ }^\circ\text{C}$ )	$T_{vj} = 25\text{ }^\circ\text{C}$		735	A	
			$T_{vj} = 125\text{ }^\circ\text{C}$		885		
			$T_{vj} = 150\text{ }^\circ\text{C}$		895		
Recovered charge	$Q_r$	$I_F = 2400\text{ A}$ , $V_R = 600\text{ V}$ , $V_{GE} = -15\text{ V}$ , $-di_F/dt = 6850\text{ A}/\mu\text{s}$ ( $T_{vj} = 150\text{ }^\circ\text{C}$ )	$T_{vj} = 25\text{ }^\circ\text{C}$		210	$\mu\text{C}$	
			$T_{vj} = 125\text{ }^\circ\text{C}$		410		
			$T_{vj} = 150\text{ }^\circ\text{C}$		475		

(table continues...)

**Table 6 (continued) Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Reverse recovery energy	$E_{rec}$	$I_F = 2400\text{ A}$ , $V_R = 600\text{ V}$ , $V_{GE} = -15\text{ V}$ , $-di_F/dt =$ $6850\text{ A}/\mu\text{s}$ ( $T_{vj} = 150\text{ °C}$ )	$T_{vj} = 25\text{ °C}$	80		mJ
			$T_{vj} = 125\text{ °C}$	150		
			$T_{vj} = 150\text{ °C}$	170		
Thermal resistance, junction to heat sink	$R_{thJH}$	per diode, Valid with IFX pre-applied Thermal Interface Material			46.4	K/kW
Temperature under switching conditions	$T_{vj\text{ op}}$		-40		150	°C

Note: Dynamic data for 3-level valid in conjunction with datasheet FF1800R23IE7, version 1.0.

$T_{vj\text{ op}}$  up to 175 °C is allowed for operations in overload conditions. For detailed specifications please refer to AN2021-11.

$R_{thJH}$  max. value is valid for  $T_C = 95\text{ °C}$ .

## 4 NTC-Thermistor

**Table 7 Characteristic values**

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	$R_{25}$	$T_{NTC} = 25\text{ °C}$		5		kΩ
Deviation of $R_{100}$	$\Delta R/R$	$T_{NTC} = 100\text{ °C}$ , $R_{100} = 493\text{ Ω}$	-5		5	%
Power dissipation	$P_{25}$	$T_{NTC} = 25\text{ °C}$			20	mW
B-value	$B_{25/50}$	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$		3375		K
B-value	$B_{25/80}$	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$		3411		K
B-value	$B_{25/100}$	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$		3433		K

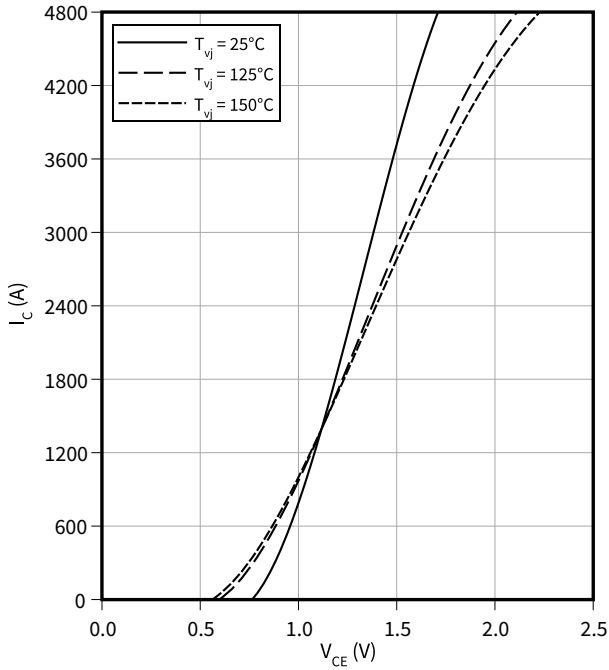
Note: For detailed specifications please refer to AN2009-10.

## 5 Characteristics diagrams

### Output characteristic (typical), IGBT, 3-Level

$$I_C = f(V_{CE})$$

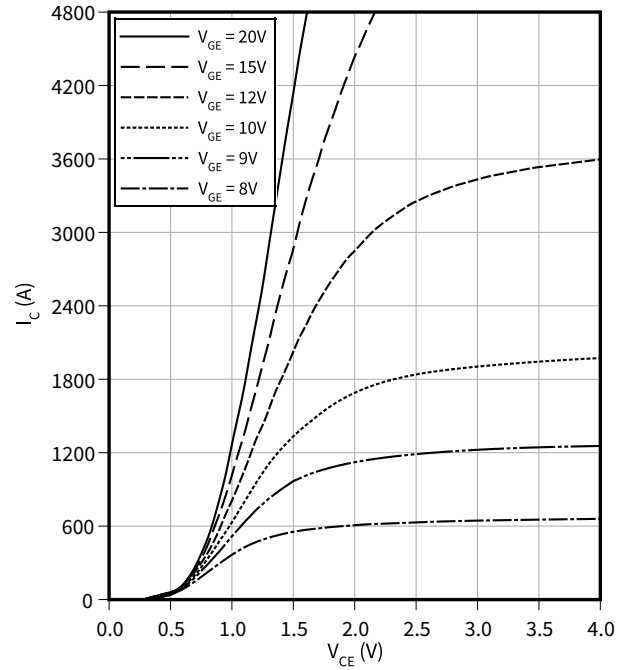
$$V_{GE} = 15 \text{ V}$$



### Output characteristic field (typical), IGBT, 3-Level

$$I_C = f(V_{CE})$$

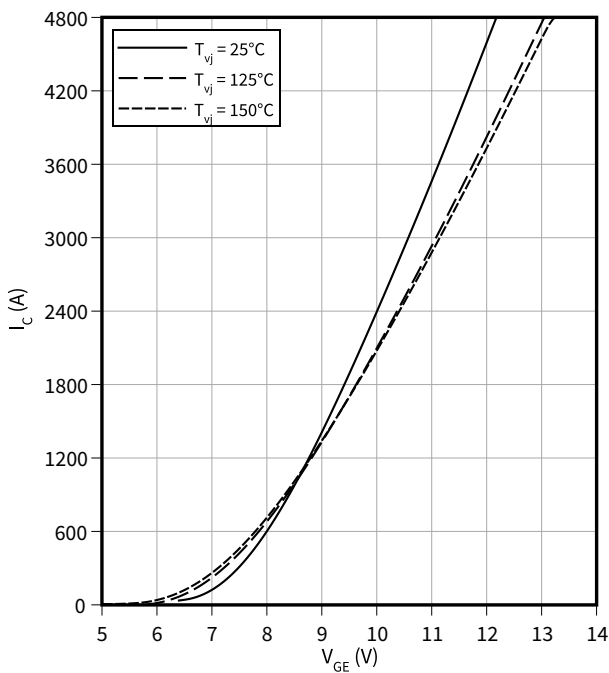
$$T_{vj} = 150 \text{ °C}$$



### Transfer characteristic (typical), IGBT, 3-Level

$$I_C = f(V_{GE})$$

$$V_{CE} = 20 \text{ V}$$

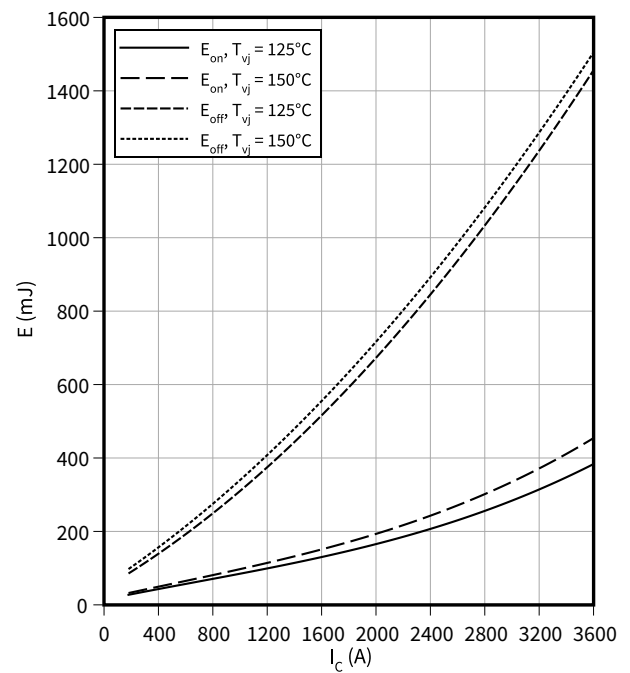


### Switching losses (typical), IGBT, 3-Level

$$E = f(I_C)$$

$$R_{Goff} = 3.3 \text{ } \Omega, R_{Gon} = 0.4 \text{ } \Omega, V_{CE} = 600 \text{ V}, V_{GE} = \pm 15 \text{ V}$$

$I_C$  is limited to 3600A by FF1800R23IE7 module.

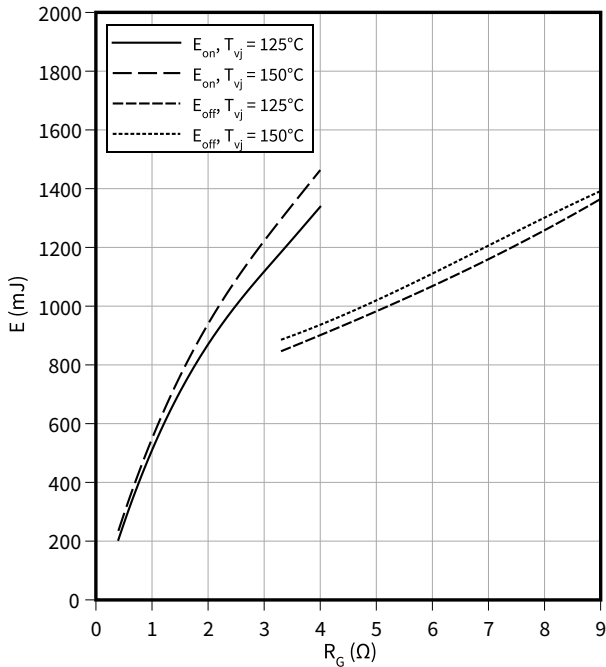


5 Characteristics diagrams

**Switching losses (typical), IGBT, 3-Level**

$E = f(R_G)$

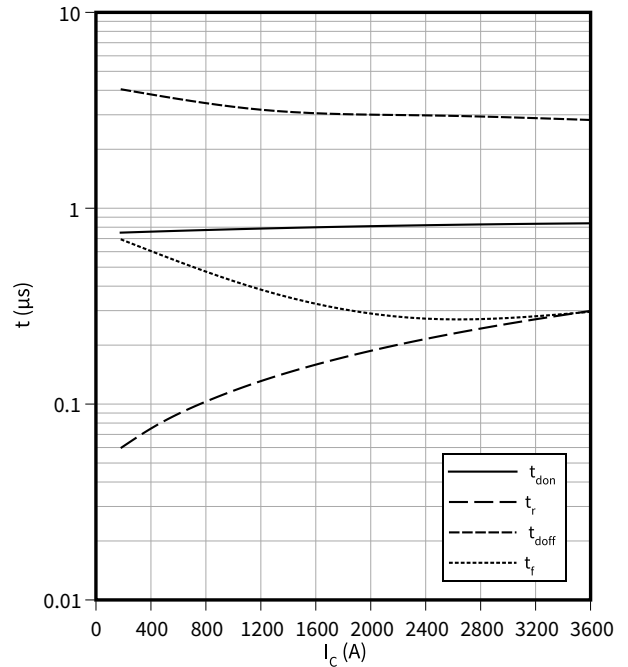
$I_C = 2400 \text{ A}$ ,  $V_{CE} = 600 \text{ V}$ ,  $V_{GE} = \pm 15 \text{ V}$



**Switching times (typical), IGBT, 3-Level**

$t = f(I_C)$

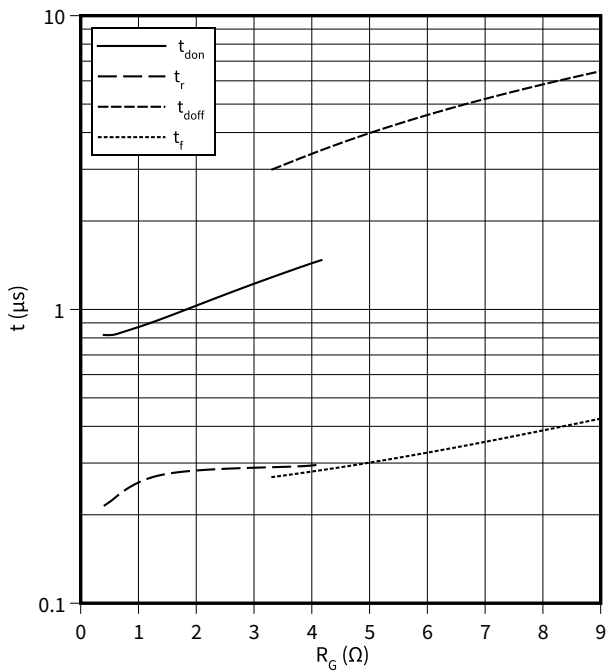
$R_{Goff} = 3.3 \Omega$ ,  $R_{Gon} = 0.4 \Omega$ ,  $V_{CE} = 600 \text{ V}$ ,  $V_{GE} = \pm 15 \text{ V}$ ,  $T_{vj} = 150 \text{ °C}$



**Switching times (typical), IGBT, 3-Level**

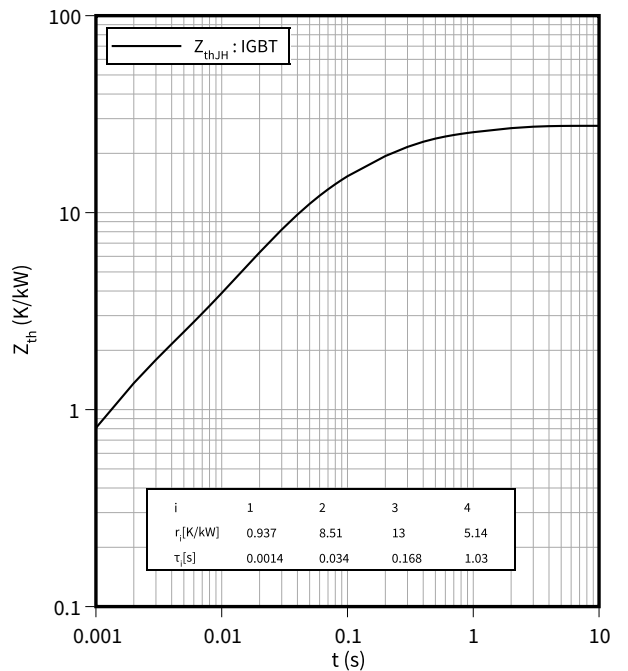
$t = f(R_G)$

$I_C = 2400 \text{ A}$ ,  $V_{CE} = 600 \text{ V}$ ,  $V_{GE} = \pm 15 \text{ V}$ ,  $T_{vj} = 150 \text{ °C}$



**Transient thermal impedance, IGBT, 3-Level**

$Z_{th} = f(t)$



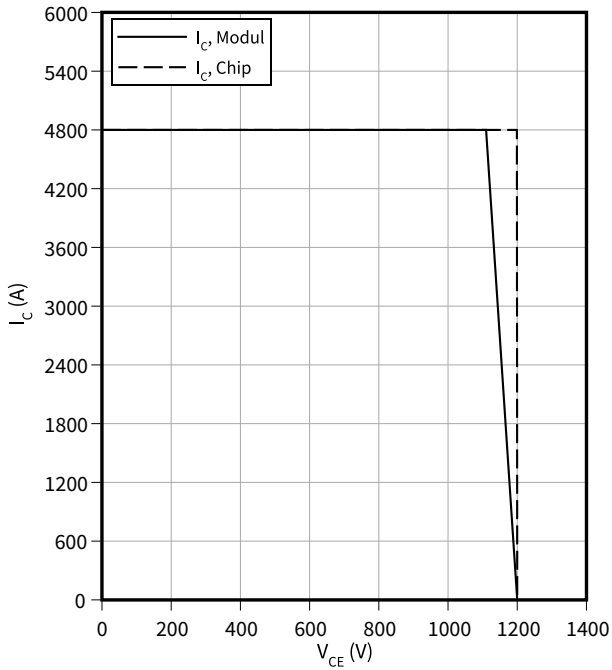


5 Characteristics diagrams

**Reverse bias safe operating area (RBSOA), IGBT, 3-Level**

$I_C = f(V_{CE})$

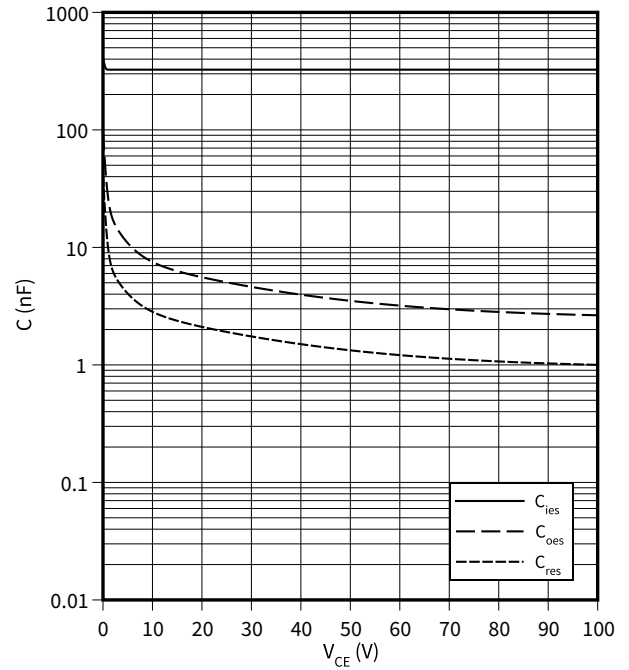
$R_{Goff} = 3.3 \Omega$ ,  $V_{GE} = 15 \text{ V}$ ,  $T_{vj} = 150 \text{ }^\circ\text{C}$



**Capacity characteristic (typical), IGBT, 3-Level**

$C = f(V_{CE})$

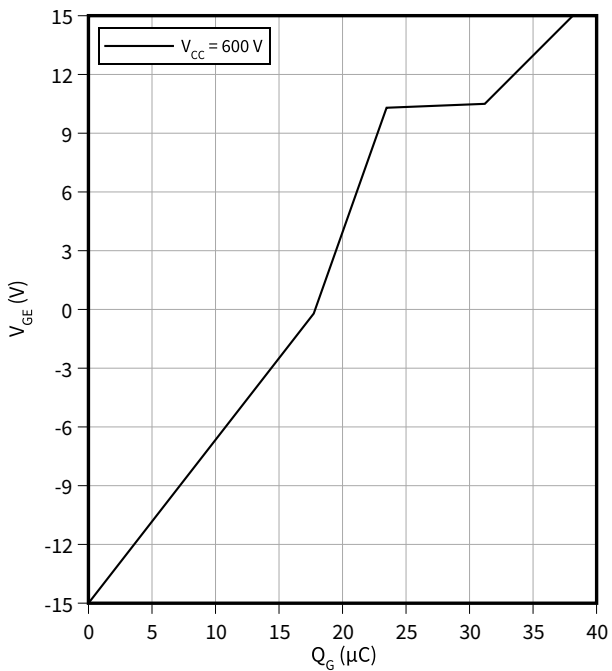
$f = 100 \text{ kHz}$ ,  $V_{GE} = 0 \text{ V}$ ,  $T_{vj} = 25 \text{ }^\circ\text{C}$



**Gate charge characteristic (typical), IGBT, 3-Level**

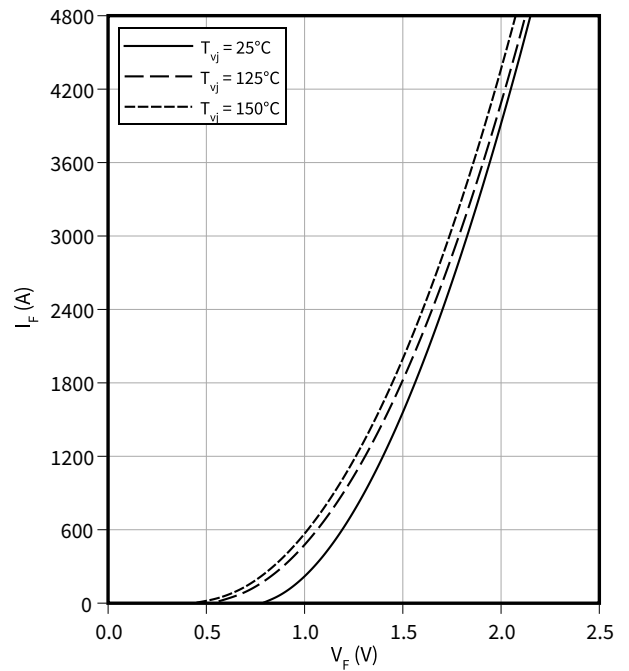
$V_{GE} = f(Q_G)$

$I_C = 2400 \text{ A}$ ,  $T_{vj} = 25 \text{ }^\circ\text{C}$



**Forward characteristic (typical), Diode, 3-Level**

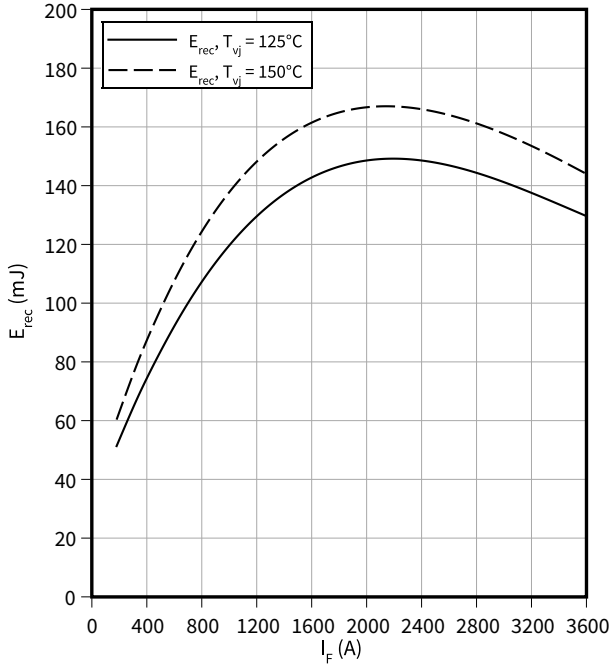
$I_F = f(V_F)$



5 Characteristics diagrams

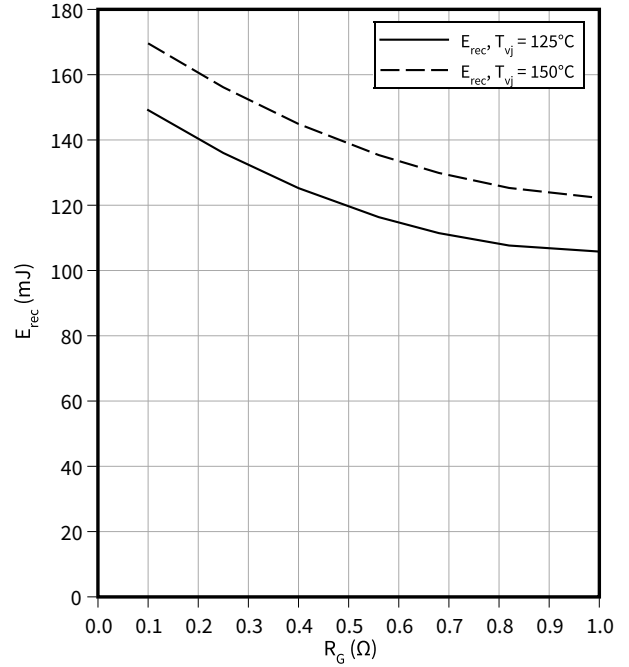
**Switching losses (typical), Diode, 3-Level**

$E_{rec} = f(I_F)$   
 $V_{CE} = 600\text{ V}, R_{Gon} = R_{Gon}(IGBT)$



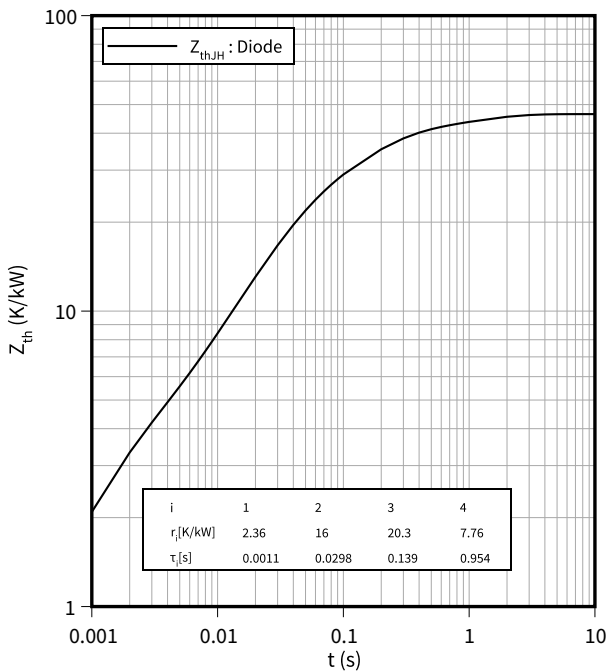
**Switching losses (typical), Diode, 3-Level**

$E_{rec} = f(R_G)$   
 $V_{CE} = 600\text{ V}, I_F = 2400\text{ A}$



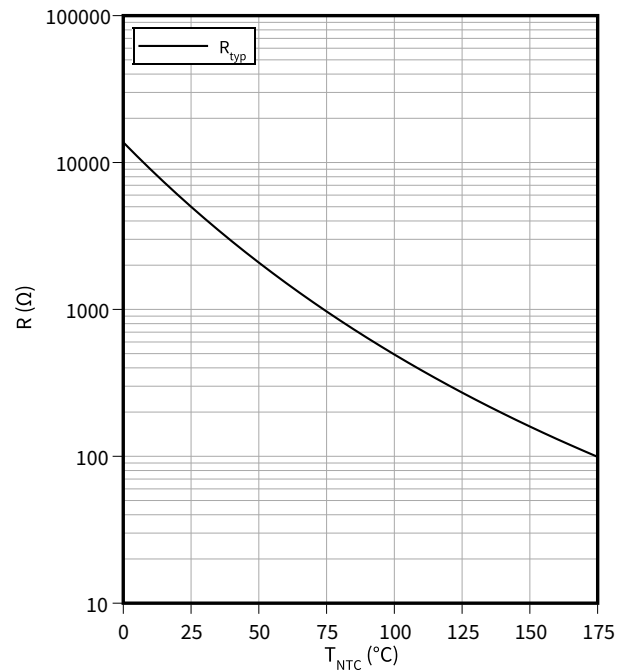
**Transient thermal impedance, Diode, 3-Level**

$Z_{th} = f(t)$



**Temperature characteristic (typical), NTC-Thermistor**

$R = f(T_{NTC})$



## 6 Circuit diagram

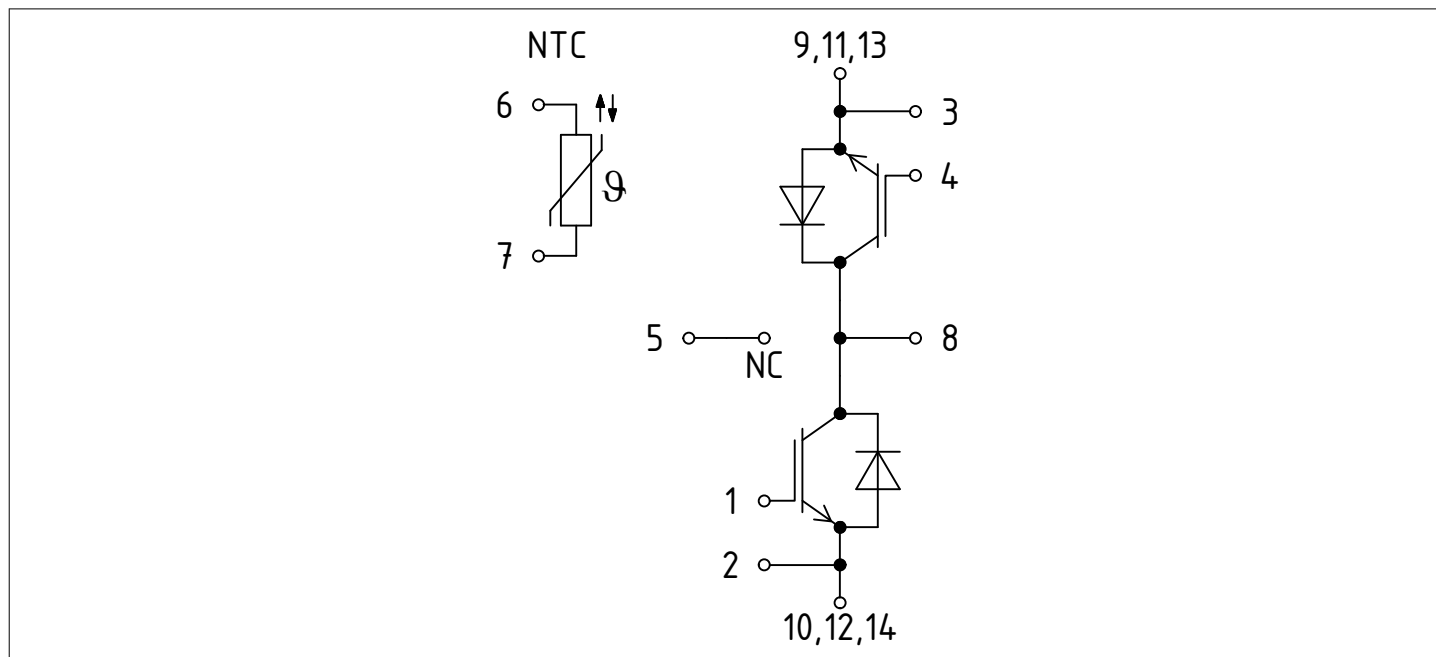


Figure 1

## 7 Package outlines

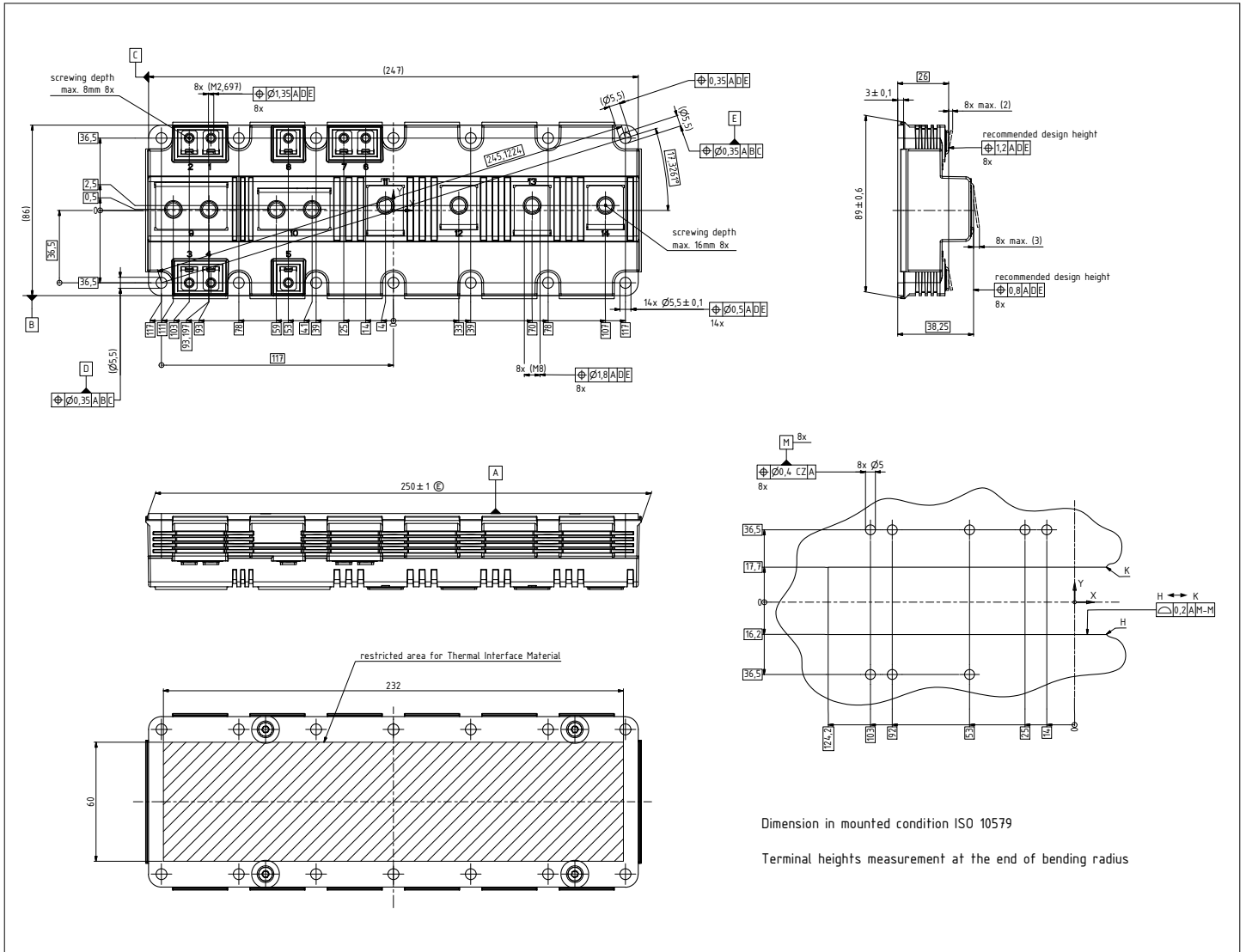


Figure 2

## 8 Module label code

Module label code			
Code format	Data Matrix	Barcode Code128	
Encoding	ASCII text	Code Set A	
Symbol size	16x16	23 digits	
Standard	IEC24720 and IEC16022	IEC8859-1	
Code content	<i>Content</i>	<i>Digit</i>	<i>Example</i>
	Module serial number	1 - 5	71549
	Module material number	6 - 11	142846
	Production order number	12 - 19	55054991
	Date code (production year)	20 - 21	15
	Date code (production week)	22 - 23	30
Example	 		
	71549142846550549911530		71549142846550549911530

**Figure 3**

## Revision history

Document revision	Date of release	Description of changes
1.00	2021-04-15	Final datasheet
1.10	2022-03-17	Final datasheet - update to FF1800R23IE7 Rev. 1.0; Extension of diagrams to 4800A (except of dynamic data, which is limited by FF1800R23IE7)

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